

**0.2A SBR<sup>®</sup>  
Super Barrier Rectifier**
**NEW PRODUCT**
**Features**

- Ultra Low Leakage Current
- Excellent High Temperature Stability
- Patented Super Barrier Rectifier Technology
- Soft, Fast Switching Capability
- 175°C Operating Junction Temperature
- **Lead Free Finish, RoHS Compliant (Note 1)**
- **“Green” Molding Compound (No Br, Sb)**

**Mechanical Data**

- Case: DFN1006-2
- Case Material: Molded Plastic, “Green” Molding compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Polarity Indicator: Cathode Dot
- Terminals: Finish - NiPdAu annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 **(e3)**
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.001 grams (Approx.)

**Maximum Ratings @ T<sub>A</sub> = 25°C unless otherwise specified**

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

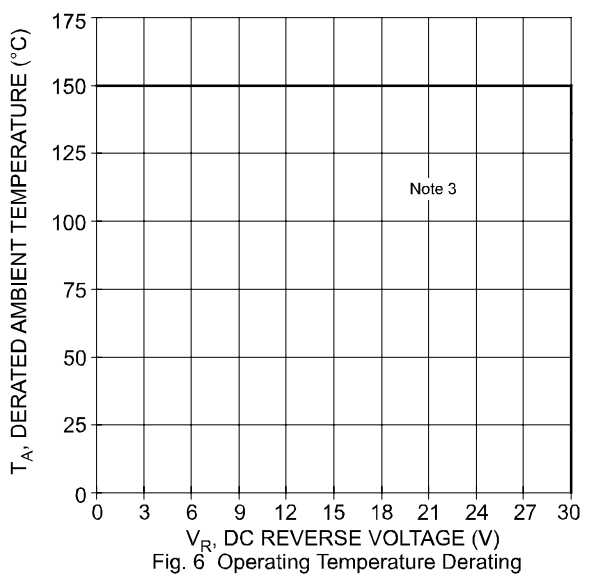
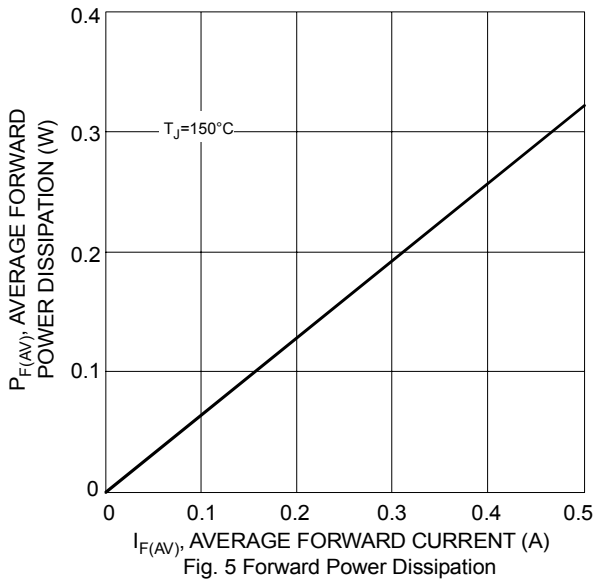
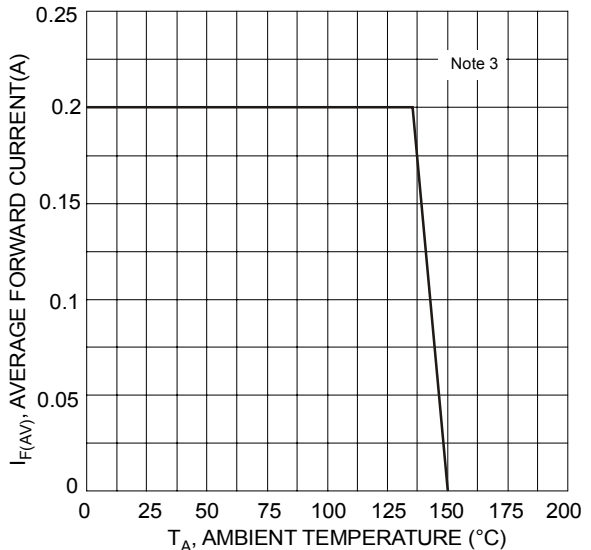
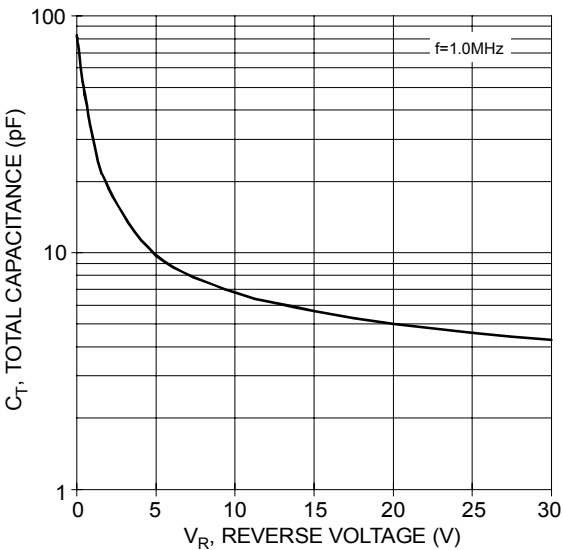
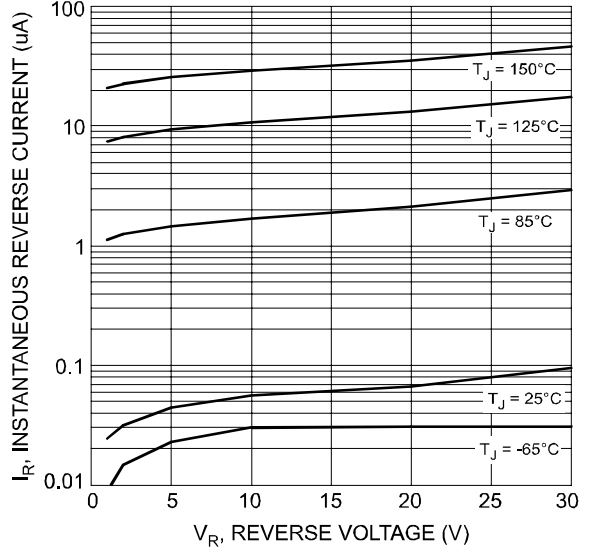
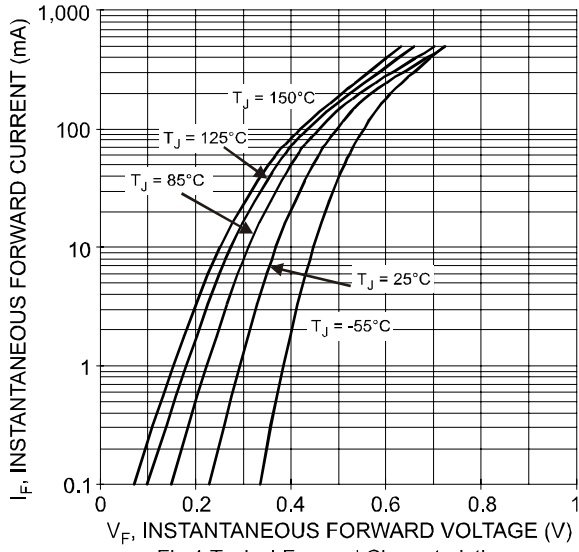
Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	30	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>RM</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	21	V
Average Rectified Output Current (See Figure 1)	I <sub>O</sub>	0.2	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	5.0	A
Maximum Thermal Resistance	R <sub>θJS</sub>	18	°C/W
Thermal Resistance Junction to Soldering (Note 2)	R <sub>θJA</sub>	263	
Thermal Resistance Junction to Ambient (Note 3)			
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +175	°C

**Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified**

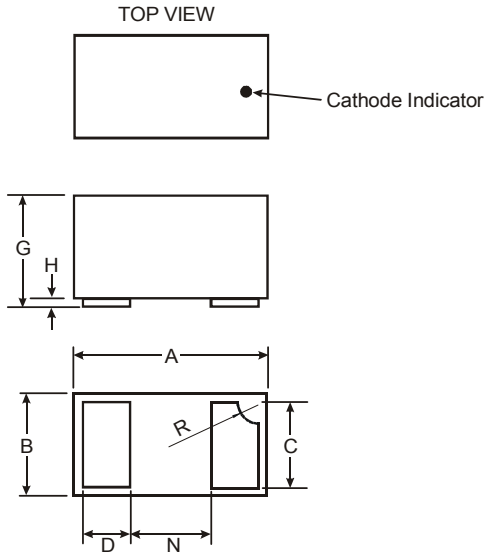
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 4)	V <sub>(BR)R</sub>	30	-	-	V	I <sub>R</sub> = 400 μA
Forward Voltage Drop	V <sub>F</sub>	-	0.50	0.54	V	I <sub>F</sub> = 0.1A, T <sub>J</sub> = 25°C
			0.42	0.45		I <sub>F</sub> = 0.1A, T <sub>J</sub> = 150°C
			0.57	0.61		I <sub>F</sub> = 0.2A, T <sub>J</sub> = 25°C
			0.51	0.54		I <sub>F</sub> = 0.2A, T <sub>J</sub> = 150°C
Leakage Current (Note 4)	I <sub>R</sub>	-	0.1	0.5	μA	V <sub>R</sub> = 30V, T <sub>J</sub> = 25°C V <sub>R</sub> = 30V, T <sub>J</sub> = 150°C

- Notes:
1. RoHS revision 13.2.2003. High temperature solder exemption applied, see *EU Directive Annex Note 7*.
  2. Theoretical R<sub>θJS</sub> calculated from the top center of the die straight down to the PCB cathode tab solder junction.
  3. FR-4 PCB, 2oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>.
  4. Short duration pulse test used to minimize self-heating effect.

**SBR02M30LP**



**Package Outline Drawing**



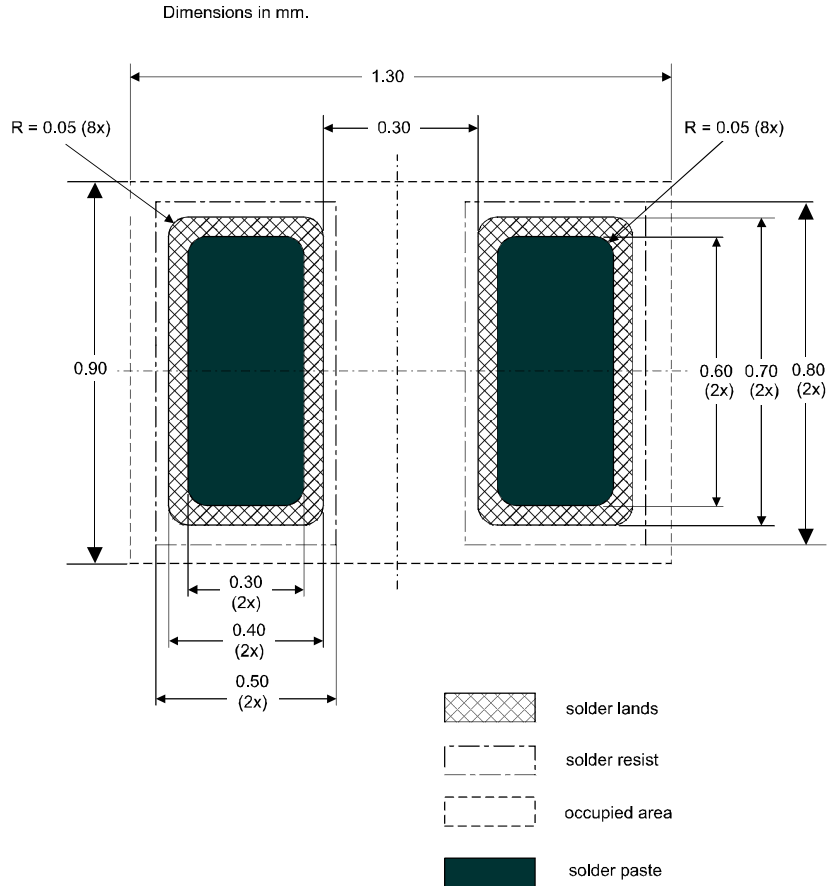
DFN1006-2			
Dim	Min	Max	Typ
A	0.95	1.075	1.00
B	0.55	0.675	0.60
C	0.45	0.55	0.50
D	0.20	0.30	0.25
G	0.47	0.53	0.50
H	0	0.05	0.03
N	—	—	0.40
R	0.05	0.15	0.10
All Dimensions in mm			

**Marking, Polarity, Weight & Ordering Information**

SBR02M30LP	Case Style (DFN1006-2)		Marking	Weight
				0.001g (approx.)

Ordering Information	Date Code
SBR02M30LP-7 3000/Tape & Reel	23 = Product Type Marking Code Dot Denotes Cathode Side

**Suggested Pad Layout**



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